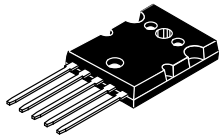


MECHANICAL CASE OUTLINE PACKAGE DIMENSIONS

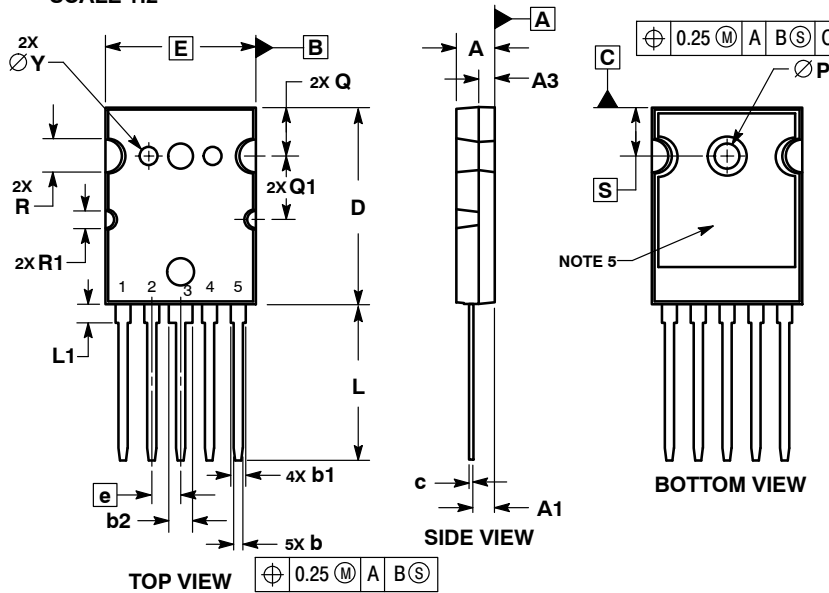
ON Semiconductor®



TO-264, 5-LEAD CASE 340AA ISSUE A

DATE 04 FEB 2013

SCALE 1:2



NOTES:

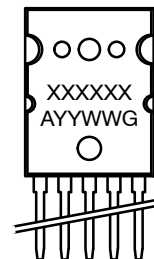
1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. DIMENSION b APPLIES BETWEEN 2.50 AND 3.81 FROM THE LEAD TIP.
4. DIMENSION S APPLIES TO THE MOUNTING HOLE (ØP). DIMENSION Q APPLIES TO THE NOTCHES (2X R).
5. THERMAL PAD SIZE AND SHAPE MAY VARY WITHIN THE AREA DEFINED BY DIMENSIONS D AND E.

DIM	MILLIMETERS	
	MIN	MAX
A	4.70	5.31
A1	2.50	3.10
A3	2.00 REF	
b	1.10	1.50
b1	2.00 REF	
b2	3.00 REF	
c	0.43	0.74
D	25.58	26.59
E	19.30	20.29
e	3.81 BSC	
L	19.79	21.39
L1	2.10	2.30
P	3.00	3.51
Q	5.80	6.20
Q1	8.80	9.20
R	4.00 REF	
R1	2.00 REF	
S	9.00 BSC	
Y	1.80 REF	

STYLE 1:

- PIN 1. BASE
- 2. EMITTER
- 3. COLLECTOR
- 4. ANODE
- 5. CATHODE

GENERIC MARKING DIAGRAM*



- XXXXXX = Specific Device Code
- A = Assembly Location
- YY = Year
- WW = Work Week
- G = Pb-Free Package

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "▪", may or may not be present.

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STATUS:	ON SEMICONDUCTOR STANDARD	
NEW STANDARD:		
DESCRIPTION:	TO-264, 5-LEAD	PAGE 1 OF 2

